

REMARKS

Claims 1–18 are pending in the present application.

Claims 1–9, 11–12, 14 and 17 were amended herein. Claims 8–9 were amended to correct errors therein identified in the Office Action.

Reconsideration of the claims is respectfully requested.

35 U.S.C. § 103 (Obviousness)

Claims 1–4, 8, 10 and 12–13 were rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 4,894,707 to *Yamawaki et al* in view of U.S. Patent No. 6,252,252 to *Kunii et al*. Claim 9 was rejected under 35 U.S.C. § 103(a) as being unpatentable over *Yamawaki et al* and *Kunii et al* in view of U.S. Patent No. 5,814,881 to *Alagaratnam et al*. Claims 17–18 were rejected under 35 U.S.C. § 103(a) as being unpatentable over *Yamawaki et al* in view of U.S. Patent No. 5,384,286 to *Hirai*. These rejections are respectfully traversed.

Independent claim 1 recites “photosensors formed in a line along a length of the integrated circuit.” Similarly, independent claims 8 and 13 each recite “a plurality of photosensitive devices linearly aligned along a length of an upper surface of the integrated circuit die” and “an array of photosensors linearly aligned along a length of a surface region of an integrated circuit die,” respectively. In the present invention, photosensors are included along an entire length of an integrated circuit die, so that multiple die mounted in contact with each other with the photosensors aligned form a substantially continuous array. Such a feature is not found in the cited references.

Independent claim 17 recites that each cavity includes “a first surface contacting a surface region of the integrated circuit die over a plurality of photosensors therein” when the lead frame strip is mounted within the mold, to prevent encapsulate material from adhering to that surface region. Such a feature is not found in the cited references.

Therefore, the rejection of claims 1–4, 8–10, 12–13 and 17–18 under 35 U.S.C. § 103 has been overcome.

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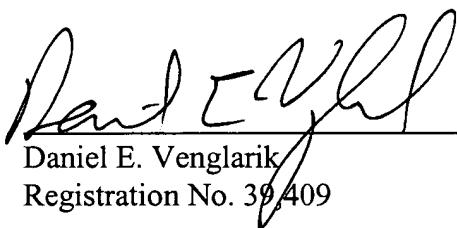
If any issues arise, or if the Examiner has any suggestions for expediting allowance of this Application, the Applicant respectfully invites the Examiner to contact the undersigned at the telephone number indicated below or at dvenglarik@davismunck.com.

The Commissioner is hereby authorized to charge any additional fees connected with this communication or credit any overpayment to Deposit Account No. 50-0208.

Respectfully submitted,

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